

Machine Name : Automatic wafer grinding machine

Brand : DISCO

Machine Model : DFG8560

Stock No. : 87135

Ex-factory Date : 2005



Main Technical Parameters:

Object of action: wafer

Maximum machining wafer size: $\Phi 300\text{mm}$

spindle Number: 2

chuck Worktable number: 3

Compatible model: DFG800 SEREINes

Footage: about 1400*3190*1800mm

grinding wheel specification: diamond grinding wheel, diameter up to 300mm

Rated output power: 4.8kW

Grinding speed range: 1000-7000Rpm(general)

Grinding precision:

The thickness error in a single wafer: very small, usually controlled in the MIKRON level, such as $1.5\mu\text{m}$ below

(2) Inter-wafer thickness error: also controlled in the MIKRON level, to ensure that the batch machining wafers have a consistent thickness

③ Surface roughness: Ry value can reach $0.13\mu\text{m}$ (using #2000 grinding wheel) or $0.15\mu\text{m}$ (using #1400 grinding wheel)





CO CORPORATION		MADE IN JAPAN
Model: DFG8560	M-Code: 872128	
No.: JV1124	MFG.Date: JUN - 2007	
MAXIMUM REVOLUTION : 4000min ⁻¹		
MAXIMUM PRESSURE : 1.5MPa. 500L/min(ANR)	VOLTAGE: 200VAC±10% 3PHASE	
MAXIMUM WATER: 0.3MPa. 25L/min	WIRING CONFIGURATION: 3WIRE+2GROUND	
MAXIMUM WATER: 0.2MPa. 4L/min	FREQUENCY: 50/60Hz	
MAXIMUM WEIGHT: 4,000kg	FULL LOAD AMPS: 57A	
	MACHINE MAIN BREAKER RATING: 63A	
	AMPERE RATING OF LARGEST LOAD: 25A	
	INTERRUPT CURRENT: 35,000A. 1.0s	
	DIAGRAM NUMBER: 8JV00271,272	